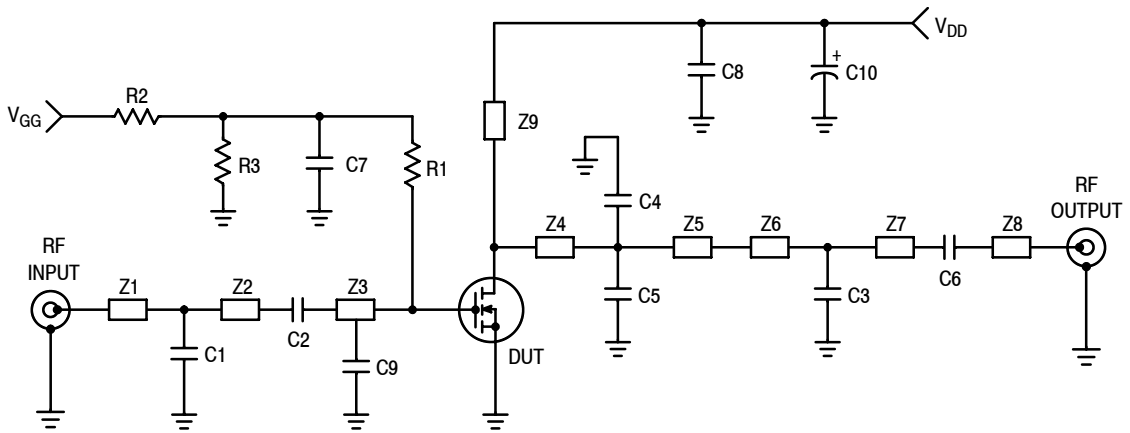


Table 4. Electrical Characteristics ($T_C = 25^\circ\text{C}$, 50 ohm system unless otherwise noted)

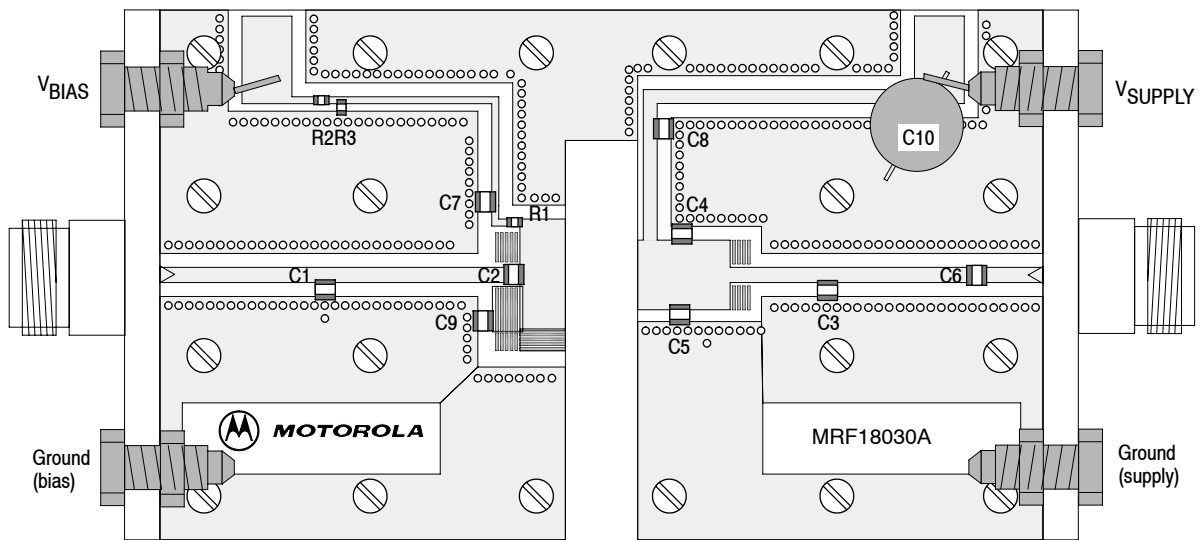
Characteristic	Symbol	Min	Typ	Max	Unit
Off Characteristics					
Drain-Source Breakdown Voltage ($V_{GS} = 0\text{ Vdc}$, $I_D = 20\ \mu\text{Adc}$)	$V_{(BR)DSS}$	65	—	—	Vdc
Zero Gate Voltage Drain Current ($V_{DS} = 26\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$)	I_{DSS}	—	—	1	μAdc
Gate-Source Leakage Current ($V_{GS} = 5\text{ Vdc}$, $V_{DS} = 0\text{ Vdc}$)	I_{GSS}	—	—	1	μAdc
On Characteristics					
Gate Threshold Voltage ($V_{DS} = 10\text{ Vdc}$, $I_D = 100\ \mu\text{Adc}$)	$V_{GS(th)}$	2	3	4	Vdc
Gate Quiescent Voltage ($V_{DS} = 26\text{ Vdc}$, $I_D = 250\ \text{mAdc}$)	$V_{GS(Q)}$	2	3.9	4.5	Vdc
Drain-Source On-Voltage ($V_{GS} = 10\text{ Vdc}$, $I_D = 1\text{ Adc}$)	$V_{DS(on)}$	—	0.29	0.4	Vdc
Forward Transconductance ($V_{DS} = 10\text{ Vdc}$, $I_D = 1\text{ Adc}$)	g_{fs}	—	2	—	S
Dynamic Characteristics					
Reverse Transfer Capacitance (1) ($V_{DS} = 26\text{ Vdc} \pm 30\ \text{mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$)	C_{rss}	—	1.3	—	pF
Functional Tests (In Freescale Test Fixture) (2)					
Output Power, 1 dB Compression Point ($V_{DD} = 26\text{ Vdc}$, $I_{DQ} = 250\ \text{mA}$, $f = 1805 - 1880\ \text{MHz}$)	P1dB	27	30	—	W
Common-Source Amplifier Power Gain @ 30 W ($V_{DD} = 26\text{ Vdc}$, $I_{DQ} = 250\ \text{mA}$, $f = 1805 - 1880\ \text{MHz}$)	G_{ps}	13	14	—	dB
Drain Efficiency @ 30 W ($V_{DD} = 26\text{ Vdc}$, $I_{DQ} = 250\ \text{mA}$, $f = 1805 - 1880\ \text{MHz}$)	η	46.5	50	—	%
Input Return Loss @ 30 W ($V_{DD} = 26\text{ Vdc}$, $I_{DQ} = 250\ \text{mA}$, $f = 1805 - 1880\ \text{MHz}$)	IRL	—	-12	-9	dB

1. Part internally matched both on input and output.
2. Device specifications obtained on a Production Test Fixture.



C1	1.8 pF, 100B Chip Capacitor	Z1	0.874" x 0.087" Microstrip
C2	0.8 pF, 100B Chip Capacitor	Z2	1.094" x 0.087" Microstrip
C3	1.0 pF, 100B Chip Capacitor	Z3	0.257" x 0.633" Microstrip
C4, C5	1.2 pF, 100B Chip Capacitors	Z4	0.189" x 0.394" Microstrip
C6, C7, C8	8.2 pF, 100B Chip Capacitors	Z5	0.335" x 0.394" Microstrip
C9	0.3 pF, 100B Chip Capacitor	Z6	0.484" x 0.087" Microstrip
C10	220 μ F, 63 V Electrolytic Capacitor	Z7	0.877" x 0.087" Microstrip
R1	1.0 k Ω , 1/8 W Chip Resistor (0805)	Z8	0.366" x 0.087" Microstrip
R2, R3	10 k Ω , 1/8 W Chip Resistors (0805)	Z9	\approx 0.600" x 0.087" Microstrip

Figure 1. 1805 - 1880 MHz Test Fixture Schematic



Freescle has begun the transition of marking Printed Circuit Boards (PCBs) with the Freescle Semiconductor signature/-logo. PCBs may have either Motorola or Freescle markings during the transition period. These changes will have no impact on form, fit or function of the current product.

Figure 2. 1805 - 1880 MHz Test Fixture Component Layout

TYPICAL CHARACTERISTICS

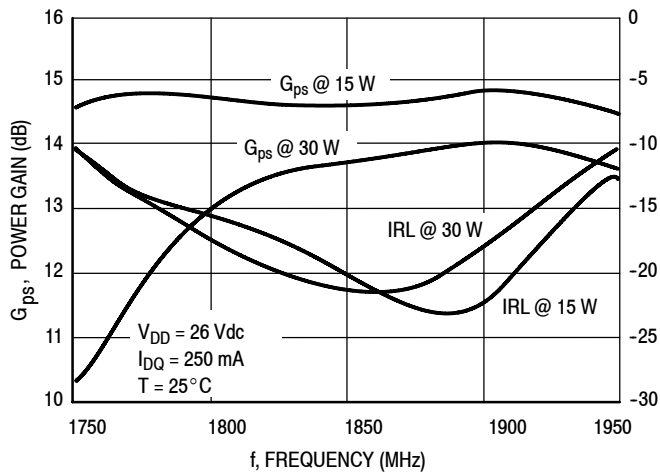


Figure 3. Wideband Gain and IRL at 30 W and 15 W Output Power

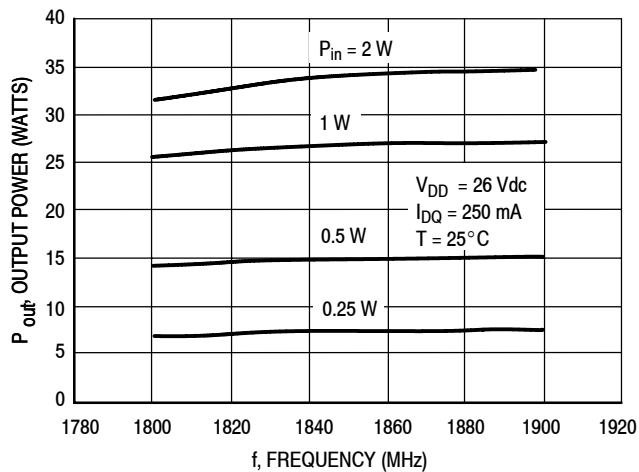


Figure 4. Output Power versus Frequency

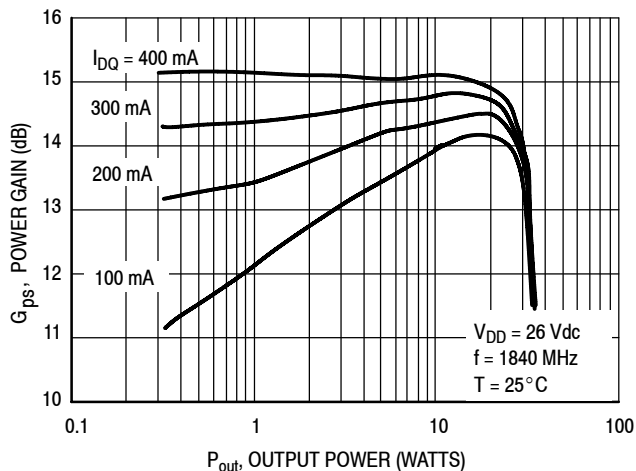


Figure 5. Power Gain versus Output Power

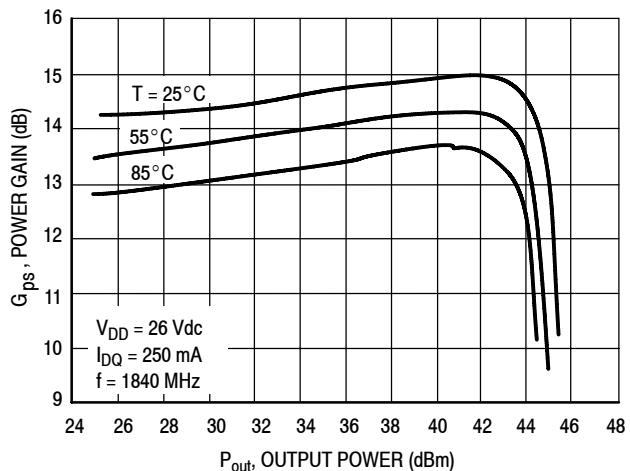


Figure 6. Power Gain versus Output Power

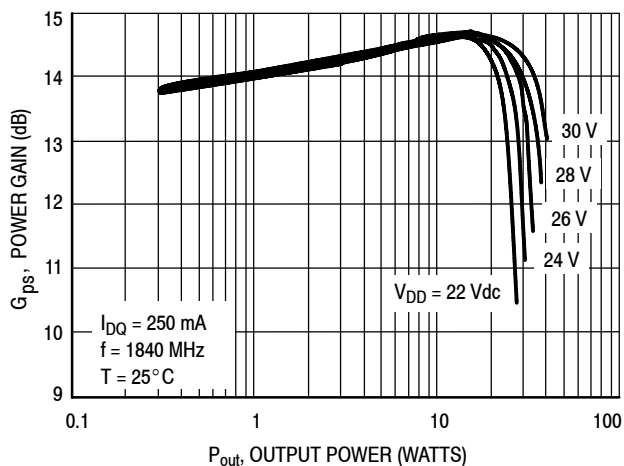


Figure 7. Power Gain versus Output Power

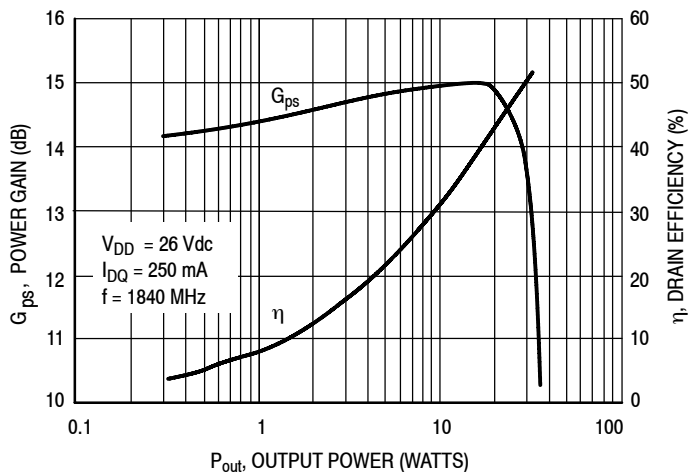
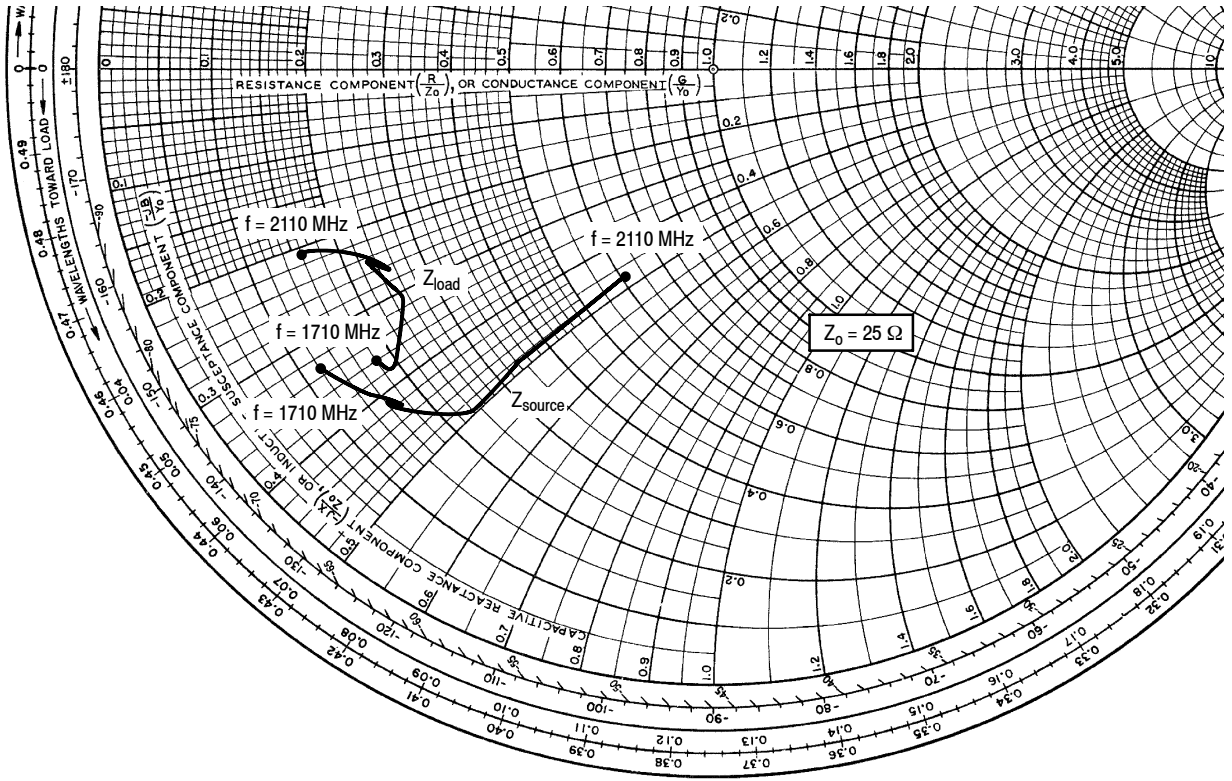


Figure 8. Power Gain and Efficiency versus Output Power

ARCHIVE INFORMATION

ARCHIVE INFORMATION



$V_{DD} = 26\text{ V}$, $I_{DQ} = 250\text{ mA}$, $P_{out} = 30\text{ W (CW)}$

f MHz	Z_{source} Ω	Z_{load} Ω
1710	$2.92 - j8.24$	$4.18 - j9.06$
1785	$3.84 - j9.75$	$4.59 - j9.46$
1805	$4.15 - j10.38$	$4.98 - j9.06$
1840	$4.04 - j10.22$	$6.10 - j7.63$
1880	$6.12 - j12.29$	$5.83 - j6.89$
1960	$6.20 - j12.29$	$5.55 - j6.33$
1990	$8.61 - j12.10$	$5.93 - j6.66$
2110	$15.19 - j11.85$	$3.82 - j5.33$

Z_{source} = Test circuit impedance as measured from gate to ground.

Z_{load} = Test circuit impedance as measured from drain to ground.

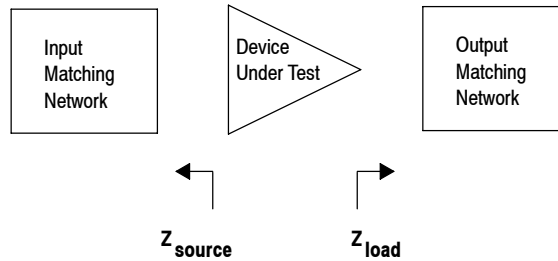


Figure 9. Series Equivalent Source and Load Impedance

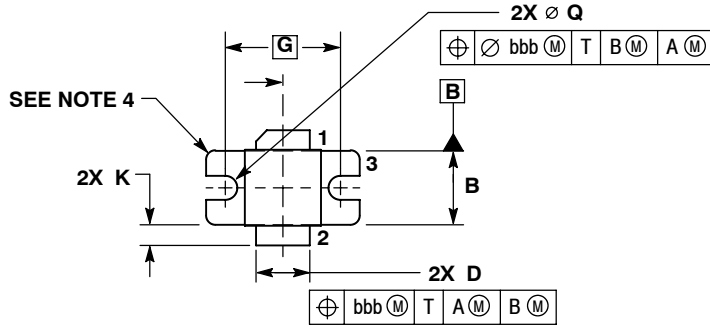
MRF18030ALR3 MRF18030ALSR3

NOTES

ARCHIVE INFORMATION

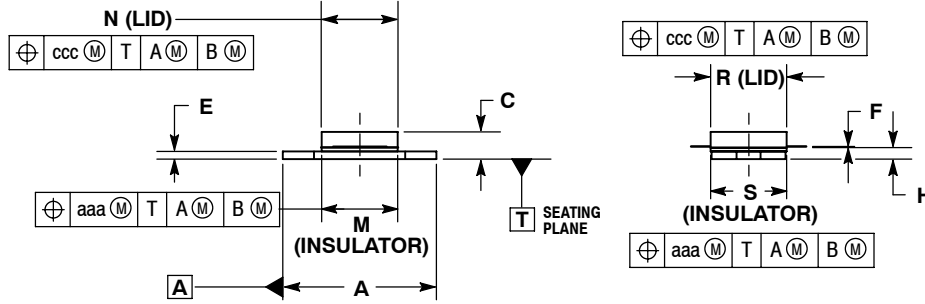
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PACKAGE DIMENSIONS



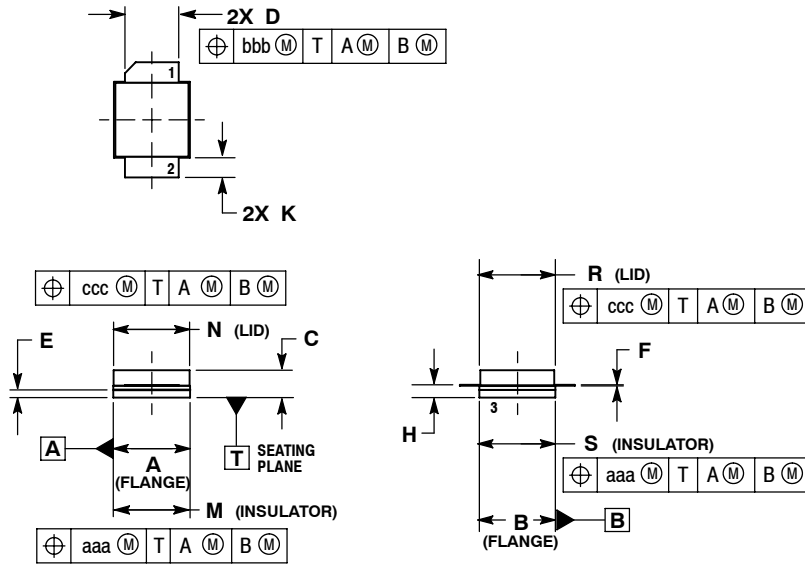
- NOTES:
1. CONTROLLING DIMENSION: INCH.
 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
 3. DIMENSION H IS MEASURED 0.030 (0.762) AWAY FROM PACKAGE BODY.
 4. INFORMATION ONLY: CORNER BREAK (4X) TO BE .060±.005 (1.52±0.13) RADIUS OR .06±.005 (1.52±0.13) x 45° CHAMFER.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.795	.805	20.19	20.44
B	.380	.390	9.65	9.9
C	.125	.163	3.17	4.14
D	.275	.285	6.98	7.24
E	.035	.045	0.89	1.14
F	.004	.006	0.10	0.15
G	.600 BSC		15.24 BSC	
H	.057	.067	1.45	1.7
K	.092	.122	2.33	3.1
M	.395	.405	10	10.3
N	.395	.405	10	10.3
Q	Ø .120	Ø .130	Ø 3.05	Ø 3.3
R	.395	.405	10	10.3
S	.395	.405	10	10.3
aaa	.005 BSC		0.127 BSC	
bbb	.010 BSC		0.254 BSC	
ccc	.015 BSC		0.381 BSC	



- STYLE 1:
 PIN 1. DRAIN
 2. GATE
 3. SOURCE

**CASE 465E-04
 ISSUE F
 NI-400
 MRF18030ALR3**



- NOTES:
1. CONTROLLING DIMENSION: INCH.
 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
 3. DIMENSION H IS MEASURED 0.030 (0.762) AWAY FROM PACKAGE BODY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.395	.405	10.03	10.29
B	.395	.405	10.03	10.29
C	.125	.163	3.18	4.14
D	.275	.285	6.98	7.24
E	.035	.045	0.89	1.14
F	.004	.006	0.10	0.15
H	.057	.067	1.45	1.70
K	.092	.122	2.34	3.10
M	.395	.405	10.03	10.29
N	.395	.405	10.03	10.29
R	.395	.405	10.03	10.29
S	.395	.405	10.03	10.29
aaa	.005 REF		0.127 REF	
bbb	.010 REF		0.254 REF	
ccc	.015 REF		0.38 REF	

- STYLE 1:
 PIN 1. DRAIN
 2. GATE
 3. SOURCE

**CASE 465F-04
 ISSUE E
 NI-400S
 MRF18030ALSR3**

REVISION HISTORY

The following table summarizes revisions to this document.

Revision	Date	Description
8	Dec. 2010	<ul style="list-style-type: none">MRF18030A Rev. 8 data sheet archived. Data sheet split due to change in part life cycle. See MRF18030A-1 Rev. 9 for MRF18030ALR3 and MRF18030A-2 Rev. 10 for MRF18030ALSR3.

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How to Reach Us:**Home Page:**

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USA/Europe or Locations Not Listed:

Freescale Semiconductor
Technical Information Center, CH370
1300 N. Alma School Road
Chandler, Arizona 85224
+1-800-521-6274 or +1-480-768-2130
support@freescale.com

Europe, Middle East, and Africa:

Freescale Halbleiter Deutschland GmbH
Technical Information Center
Schatzbogen 7
81829 Muenchen, Germany
+44 1296 380 456 (English)
+46 8 52200080 (English)
+49 89 92103 559 (German)
+33 1 69 35 48 48 (French)
support@freescale.com

Japan:

Freescale Semiconductor Japan Ltd.
Headquarters
ARCO Tower 15F
1-8-1, Shimo-Meguro, Meguro-ku,
Tokyo 153-0064
Japan
0120 191014 or +81 3 5437 9125
support.japan@freescale.com

Asia/Pacific:

Freescale Semiconductor Hong Kong Ltd.
Technical Information Center
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